



SOT1444-9

wafer level chip-scale package; 49 bumps; 3.19 mm x 3.19 mm x 0.49 mm

14 December 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	26-4-2016
Manufacturer package code	SOT1444

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	3.19	-	mm
E	package width	-	-	3.19	-	mm
A	seated height	-	-	-	0.49	mm
A ₂	package height	0.225	-	0.25	0.275	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



2. Package outline

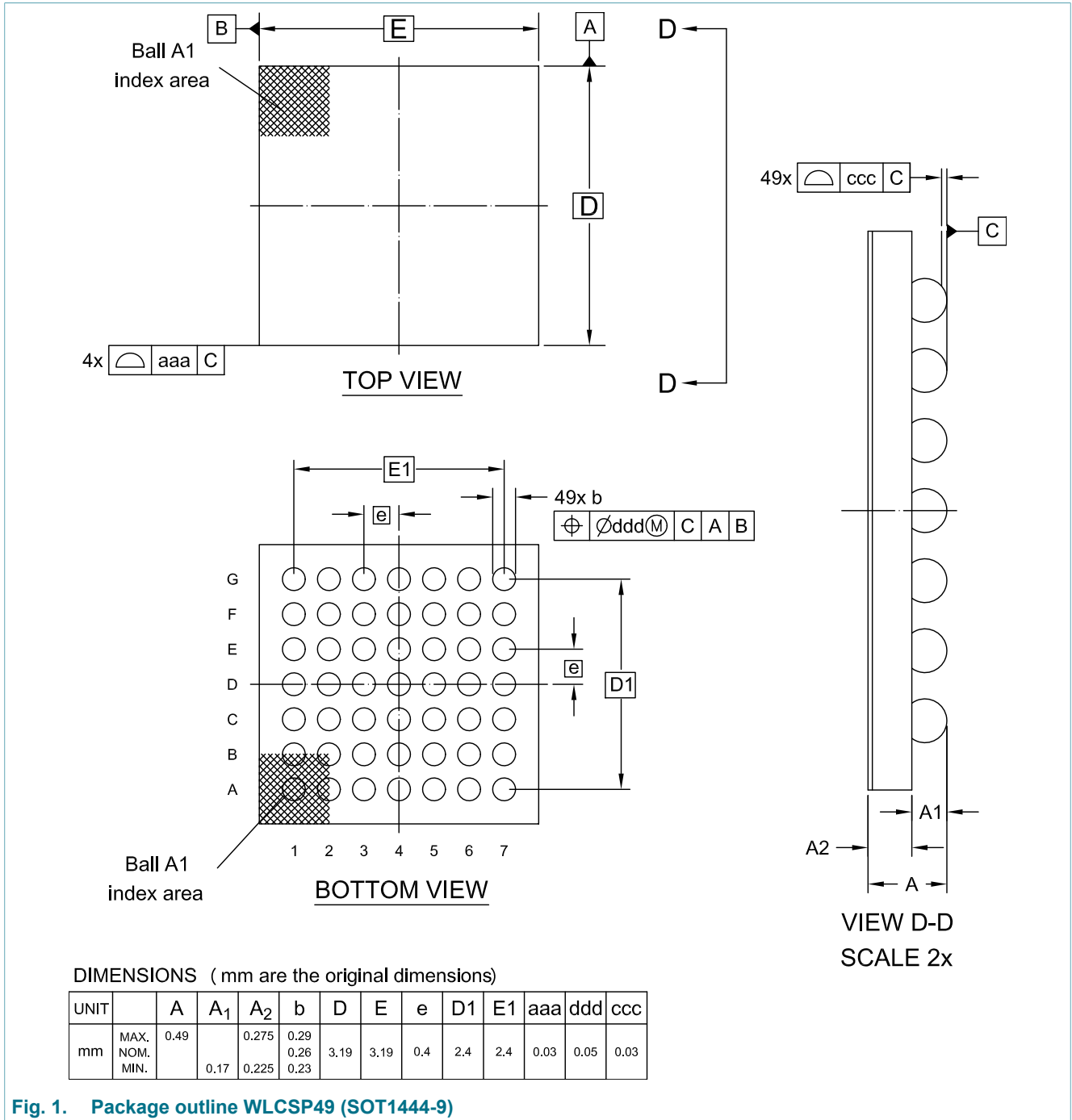


Fig. 1. Package outline WLCSP49 (SOT1444-9)

3. Legal information

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